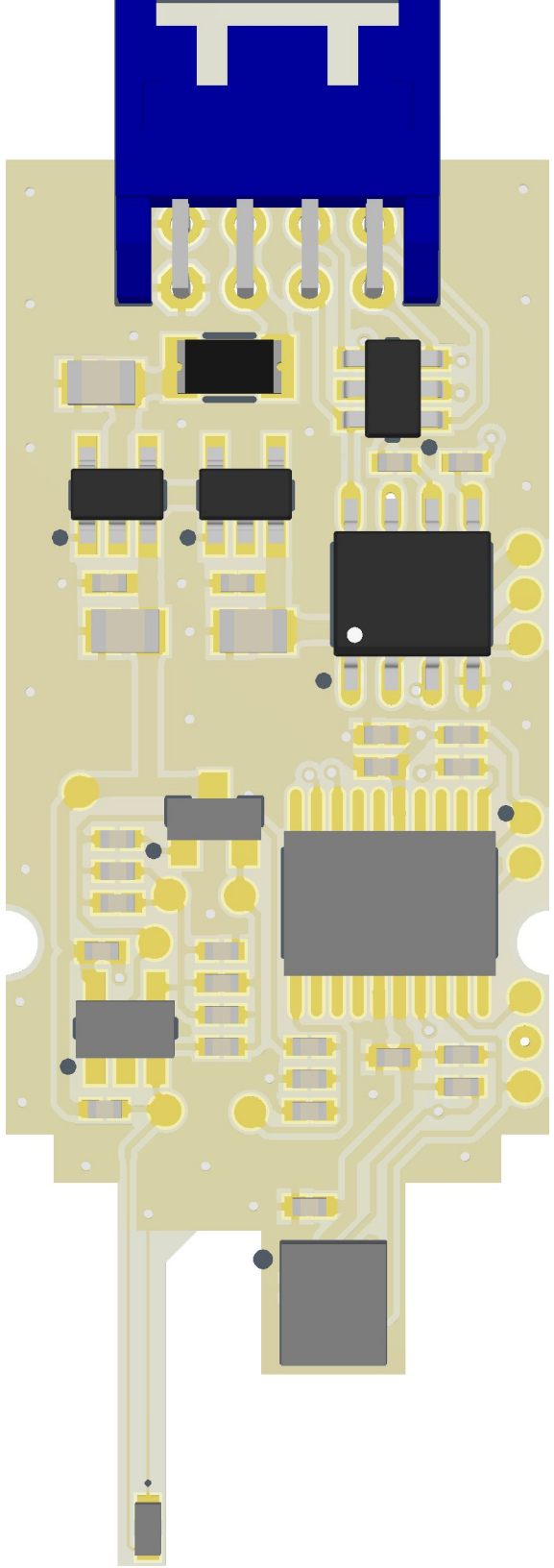
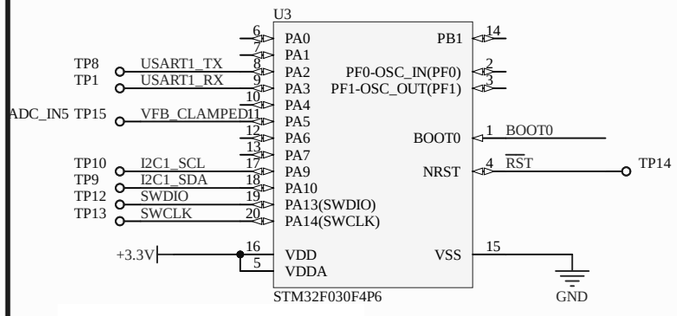
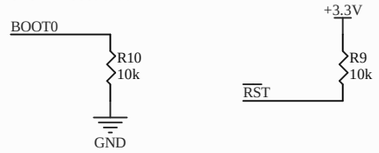


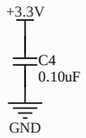
Microcontroller



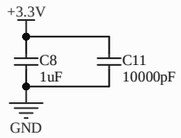
Note: Pull high for UART bootloader

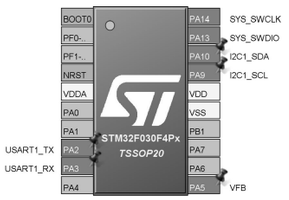


Note: Place near U1 pin 16



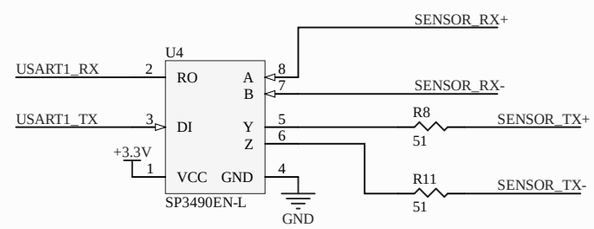
Note: Place near U1 pin 5

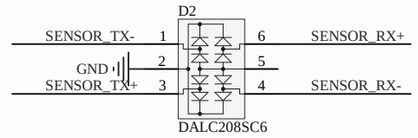


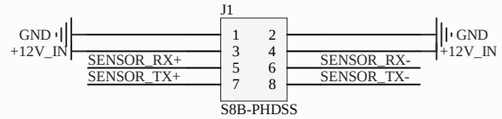


Notes:
-The microcontroller needs to sample an analog value at 100Hz, process it, and send it over a UART

Sensor board connector

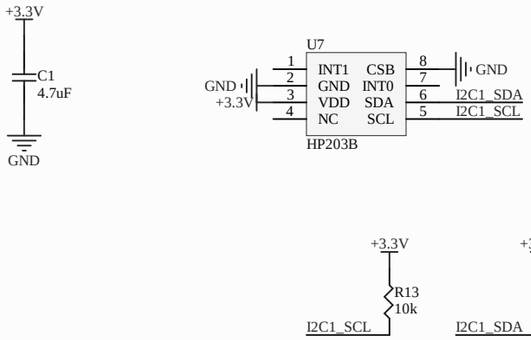






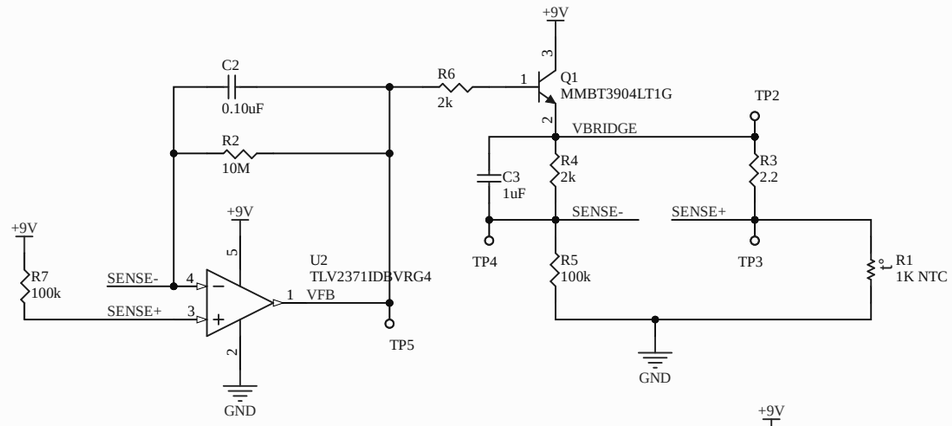
Notes:
-RJ485 Power wiring referenced from passive POE, using pinout from 802.3af Mode B
-RJ45 Data wiring referenced from DMX over Cat5
-Alternate PN for TVS: SRV05-4-P-T7, SP724AHTG, NUP4114HMR6T1G, etc

Pressure Sensor



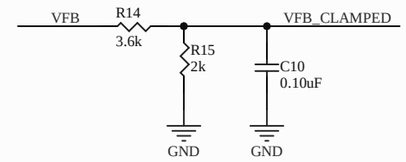
Notes:
-Maximum BIPAP output pressure is 30cm/H20 = 3 kPa
-Sensor should have ideally thousands of counts (?) of sensitivity over this range
-Sensor should withstand high Oxygen environments if possible
-Place only one sensor

Airflow Sensor



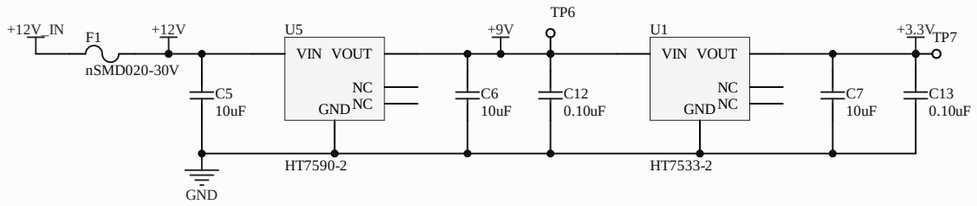
Notes:
-Air speed roughly 0 - .5m/s (could adjust by modifying the mechanical port?)
-Thermal response needs to be fast enough to detect .17-.67 Hz tidal flow
-Circuit will be exposed to Oxygen rich environment

Feedback voltage divider



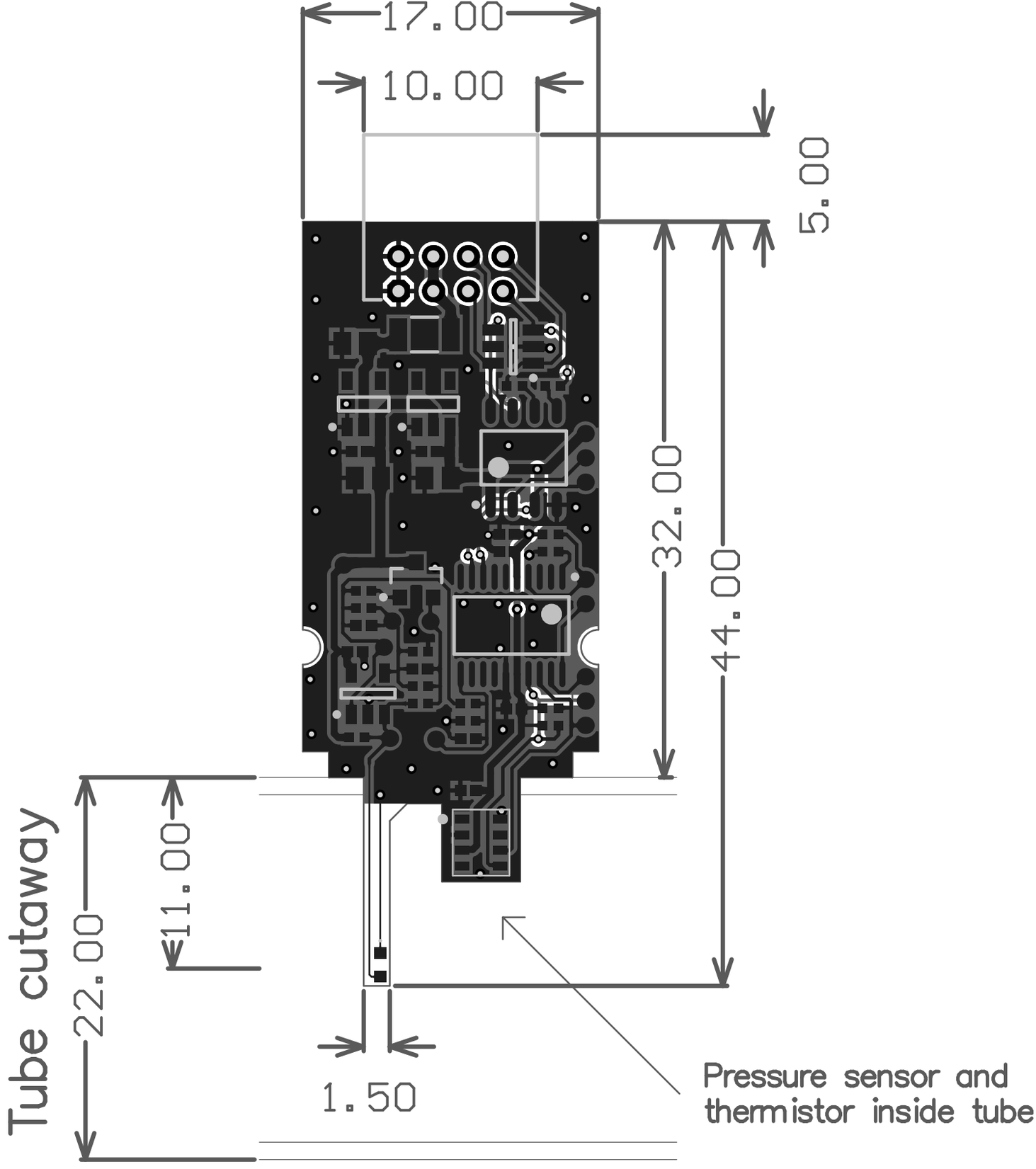
Notes:
-Voltage divider, input is max 9V so nominal max output is 3.2V
-100nF capacitor >> 18pF input capacitance of ADC
-By simulation, max input with 1% components is under 3.3V
-By simulation, 3dB rolloff is 1kHZ

Power Supply



Title: Sensor Module	
Project: sensor_module.PrjPcb	Revision: F
Date: 5/11/2020 Time: 5:32:49 PM	Sheet 1 of 1

BLIN KIN LABS



Layer	Name	Material	Thickness	Constant	Gerber
	Top Overlay				GTO
	Top Solder	Solder Resist	0.013mm	3.8	GTS
1	Top Layer	Copper	0.036mm		GTL
	Dielectric 1	FR-4	0.502mm	4.8	
2	Bottom Layer	Copper	0.036mm		GBL
	Bottom Solder	Solder Resist	0.013mm	3.8	GBS
	Bottom Overlay				GBO
Total board thickness:			0.599mm		

Design Rules Verification Report

Filename : C:\Users\matt\Dropbox\Ventilator Project\PCB\sensor_module\pcb\sensor_mod

Warnings 0
Rule Violations 138

Warnings	
Total	0

Rule Violations	
Clearance Constraint (Gap=0.2mm) (All),(All)	0
Short-Circuit Constraint (Allowed=No) (All),(All)	0
Un-Routed Net Constraint ((All))	0
Modified Polygon (Allow modified: No), (Allow shelved: No)	0
Width Constraint (Min=0.2mm) (Max=0.6mm) (Preferred=0.4mm) (All)	5
Power Plane Connect Rule(Relief Connect)(Expansion=0.508mm) (Conductor Width=0.254mm)	0
Hole Size Constraint (Min=0.025mm) (Max=2.54mm) (All)	0
Hole To Hole Clearance (Gap=0.254mm) (All),(All)	0
Minimum Solder Mask Sliver (Gap=0.254mm) (All),(All)	113
Silk To Solder Mask (Clearance=0.254mm) (IsPad),(All)	20
Silk to Silk (Clearance=0.254mm) (All),(All)	0
Net Antennae (Tolerance=0mm) (All)	0
Room sensor_module (Bounding Region = (114mm, 104mm, 134mm, 154.5mm)	0
Height Constraint (Min=0mm) (Max=25.4mm) (Prefered=12.7mm) (All)	0
Total	138

Width Constraint (Min=0.2mm) (Max=0.6mm) (Preferred=0.4mm) (All)
Width Constraint: Track (3.825mm,-11.35mm)(3.825mm,0.8mm) on Top Layer Actual Width = 0.102mm, Target Width =
Width Constraint: Track (3.825mm,-11.35mm)(3.95mm,-11.475mm) on Top Layer Actual Width = 0.102mm, Target Width
Width Constraint: Track (3.95mm,-11.475mm)(4.45mm,-11.475mm) on Top Layer Actual Width = 0.102mm, Target Width
Width Constraint: Track (4.45mm,-10.125mm)(4.45mm,-1mm) on Top Layer Actual Width = 0.102mm, Target Width = 0.2mr
Width Constraint: Track (4.45mm,-10.35mm)(4.45mm,-10.125mm) on Top Layer Actual Width = 0.102mm, Target Width =

Minimum Solder Mask Sliver (Gap=0.254mm) (All),(All)
Minimum Solder Mask Sliver Constraint: (0.017mm < 0.254mm) Between Pad C10-1(9.94mm,2.25mm) on Top Layer And Pac
Minimum Solder Mask Sliver Constraint: (0.212mm < 0.254mm) Between Pad C10-1(9.94mm,2.25mm) on Top Layer And Pac
Minimum Solder Mask Sliver Constraint: (0.227mm < 0.254mm) Between Pad C10-1(9.94mm,2.25mm) on Top Layer And Pac
Minimum Solder Mask Sliver Constraint: (0.227mm < 0.254mm) Between Pad C10-2(9.06mm,2.25mm) on Top Layer And Pac
Minimum Solder Mask Sliver Constraint: (0.212mm < 0.254mm) Between Pad C10-2(9.06mm,2.25mm) on Top Layer And Pac
Minimum Solder Mask Sliver Constraint: (0.017mm < 0.254mm) Between Pad C1-1(9.06mm,-0.75mm) on Top Layer And Pac
Minimum Solder Mask Sliver Constraint: (0.017mm < 0.254mm) Between Pad C11-1(12.19mm,13mm) on Top Layer And Pac
Minimum Solder Mask Sliver Constraint: (0.178mm < 0.254mm) Between Pad C11-1(12.19mm,13mm) on Top Layer And Pac
Minimum Solder Mask Sliver Constraint: (0.177mm < 0.254mm) Between Pad C11-1(12.19mm,13mm) on Top Layer And Pac
Minimum Solder Mask Sliver Constraint: (0.187mm < 0.254mm) Between Pad C11-1(12.19mm,13mm) on Top Layer And Pac
Minimum Solder Mask Sliver Constraint: (0.194mm < 0.254mm) Between Pad C11-1(12.19mm,13mm) on Top Layer And Pac
Minimum Solder Mask Sliver Constraint: (0.177mm < 0.254mm) Between Pad C11-2(11.31mm,13mm) on Top Layer And Pac
Minimum Solder Mask Sliver Constraint: (0.178mm < 0.254mm) Between Pad C11-2(11.31mm,13mm) on Top Layer And Pac
Minimum Solder Mask Sliver Constraint: (0.187mm < 0.254mm) Between Pad C11-2(11.31mm,13mm) on Top Layer And Pac
Minimum Solder Mask Sliver Constraint: (0.187mm < 0.254mm) Between Pad C11-2(11.31mm,13mm) on Top Layer And Pac
Minimum Solder Mask Sliver Constraint: (0.017mm < 0.254mm) Between Pad C12-1(2.81mm,18.75mm) on Top Layer And
Minimum Solder Mask Sliver Constraint: (0.017mm < 0.254mm) Between Pad C13-1(6.81mm,18.75mm) on Top Layer And
Minimum Solder Mask Sliver Constraint: (0.017mm < 0.254mm) Between Pad C2-1(3.06mm,8.75mm) on Top Layer And Pac
Minimum Solder Mask Sliver Constraint: (0.212mm < 0.254mm) Between Pad C2-1(3.06mm,8.75mm) on Top Layer And Pac
Minimum Solder Mask Sliver Constraint: (0.227mm < 0.254mm) Between Pad C2-1(3.06mm,8.75mm) on Top Layer And Pac
Minimum Solder Mask Sliver Constraint: (0.227mm < 0.254mm) Between Pad C2-2(3.94mm,8.75mm) on Top Layer And Pac
Minimum Solder Mask Sliver Constraint: (0.212mm < 0.254mm) Between Pad C2-2(3.94mm,8.75mm) on Top Layer And Pac
Minimum Solder Mask Sliver Constraint: (0.152mm < 0.254mm) Between Pad C2-2(3.94mm,8.75mm) on Top Layer And Pac
Minimum Solder Mask Sliver Constraint: (0.017mm < 0.254mm) Between Pad C3-1(7.19mm,6.25mm) on Top Layer And Pac
Minimum Solder Mask Sliver Constraint: (0.227mm < 0.254mm) Between Pad C3-1(7.19mm,6.25mm) on Top Layer And Pac
Minimum Solder Mask Sliver Constraint: (0.212mm < 0.254mm) Between Pad C3-1(7.19mm,6.25mm) on Top Layer And Pac
Minimum Solder Mask Sliver Constraint: (0.212mm < 0.254mm) Between Pad C3-1(7.19mm,6.25mm) on Top Layer And Pac
Minimum Solder Mask Sliver Constraint: (0.227mm < 0.254mm) Between Pad C3-1(7.19mm,6.25mm) on Top Layer And Pac
Minimum Solder Mask Sliver Constraint: (0.212mm < 0.254mm) Between Pad C3-2(6.31mm,6.25mm) on Top Layer And Pac
Minimum Solder Mask Sliver Constraint: (0.227mm < 0.254mm) Between Pad C3-2(6.31mm,6.25mm) on Top Layer And Pac
Minimum Solder Mask Sliver Constraint: (0.227mm < 0.254mm) Between Pad C3-2(6.31mm,6.25mm) on Top Layer And Pac
Minimum Solder Mask Sliver Constraint: (0.212mm < 0.254mm) Between Pad C3-2(6.31mm,6.25mm) on Top Layer And Pac
Minimum Solder Mask Sliver Constraint: (0.017mm < 0.254mm) Between Pad C4-1(11.685mm,3.925mm) on Top Layer And
Minimum Solder Mask Sliver Constraint: (0.017mm < 0.254mm) Between Pad C8-1(11.31mm,14mm) on Top Layer And Pac
Minimum Solder Mask Sliver Constraint: (0.017mm < 0.254mm) Between Pad C9-1(3.44mm,7.25mm) on Top Layer And Pac
Minimum Solder Mask Sliver Constraint: (0.177mm < 0.254mm) Between Pad C9-1(3.44mm,7.25mm) on Top Layer And Pac
Minimum Solder Mask Sliver Constraint: (0.162mm < 0.254mm) Between Pad C9-1(3.44mm,7.25mm) on Top Layer And Pac
Minimum Solder Mask Sliver Constraint: (0.162mm < 0.254mm) Between Pad C9-2(2.56mm,7.25mm) on Top Layer And Pac
Minimum Solder Mask Sliver Constraint: (0.147mm < 0.254mm) Between Pad D2-1(13.25mm,23.85mm) on Top Layer And
Minimum Solder Mask Sliver Constraint: (0.147mm < 0.254mm) Between Pad D2-2(13.25mm,24.8mm) on Top Layer And Pac
Minimum Solder Mask Sliver Constraint: (0.147mm < 0.254mm) Between Pad D2-4(10.95mm,25.75mm) on Top Layer And
Minimum Solder Mask Sliver Constraint: (0.147mm < 0.254mm) Between Pad D2-5(10.95mm,24.8mm) on Top Layer And Pac
Minimum Solder Mask Sliver Constraint: (0.222mm < 0.254mm) Between Pad Q1-1(5.575mm,10.375mm) on Top Layer And
Minimum Solder Mask Sliver Constraint: (0.247mm < 0.254mm) Between Pad Q1-2(7.475mm,10.375mm) on Top Layer And
Minimum Solder Mask Sliver Constraint: (0.147mm < 0.254mm) Between Pad R10-1(14.7mm,13mm) on Top Layer And Pac
Minimum Solder Mask Sliver Constraint: (0.247mm < 0.254mm) Between Pad R10-1(14.7mm,13mm) on Top Layer And Pac
Minimum Solder Mask Sliver Constraint: (0.222mm < 0.254mm) Between Pad R10-1(14.7mm,13mm) on Top Layer And Pac
Minimum Solder Mask Sliver Constraint: (0.224mm < 0.254mm) Between Pad R10-1(14.7mm,13mm) on Top Layer And Pac
Minimum Solder Mask Sliver Constraint: (0.247mm < 0.254mm) Between Pad R10-2(13.8mm,13mm) on Top Layer And Pac
Minimum Solder Mask Sliver Constraint: (0.231mm < 0.254mm) Between Pad R10-2(13.8mm,13mm) on Top Layer And Pac
Minimum Solder Mask Sliver Constraint: (0.222mm < 0.254mm) Between Pad R10-2(13.8mm,13mm) on Top Layer And Pac
Minimum Solder Mask Sliver Constraint: (0.147mm < 0.254mm) Between Pad R11-1(12.625mm,22.525mm) on Top Layer And

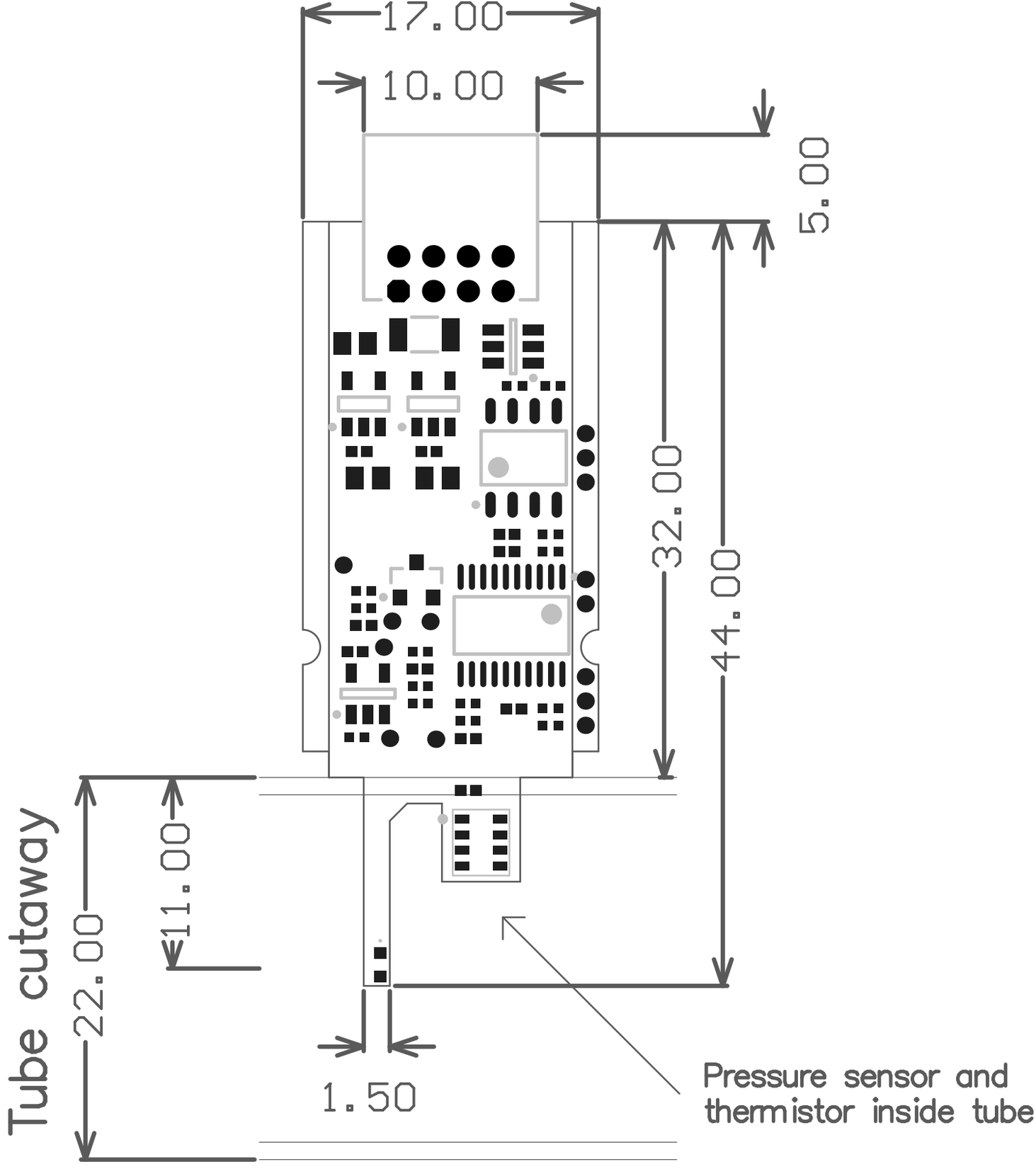
Minimum Solder Mask Sliver (Gap=0.254mm) (All),(All)
Minimum Solder Mask Sliver Constraint: (0.224mm < 0.254mm) Between Pad R11-1(12.625mm,22.525mm) on Top Layer And
Minimum Solder Mask Sliver Constraint: (0.197mm < 0.254mm) Between Pad R11-2(11.725mm,22.525mm) on Top Layer And
Minimum Solder Mask Sliver Constraint: (0.147mm < 0.254mm) Between Pad R12-1(14.7mm,4mm) on Top Layer And Pad
Minimum Solder Mask Sliver Constraint: (0.247mm < 0.254mm) Between Pad R12-1(14.7mm,4mm) on Top Layer And Pad
Minimum Solder Mask Sliver Constraint: (0.247mm < 0.254mm) Between Pad R12-2(13.8mm,4mm) on Top Layer And Pad
Minimum Solder Mask Sliver Constraint: (0.147mm < 0.254mm) Between Pad R13-1(14.7mm,3mm) on Top Layer And Pad
Minimum Solder Mask Sliver Constraint: (0.147mm < 0.254mm) Between Pad R14-1(9.95mm,4.25mm) on Top Layer And Pad
Minimum Solder Mask Sliver Constraint: (0.247mm < 0.254mm) Between Pad R14-1(9.95mm,4.25mm) on Top Layer And Pad
Minimum Solder Mask Sliver Constraint: (0.247mm < 0.254mm) Between Pad R14-2(9.05mm,4.25mm) on Top Layer And Pad
Minimum Solder Mask Sliver Constraint: (0.147mm < 0.254mm) Between Pad R15-1(9.95mm,3.25mm) on Top Layer And Pad
Minimum Solder Mask Sliver Constraint: (0.147mm < 0.254mm) Between Pad R2-1(3.05mm,9.75mm) on Top Layer And Pad
Minimum Solder Mask Sliver Constraint: (0.247mm < 0.254mm) Between Pad R2-1(3.05mm,9.75mm) on Top Layer And Pad
Minimum Solder Mask Sliver Constraint: (0.247mm < 0.254mm) Between Pad R2-2(3.95mm,9.75mm) on Top Layer And Pad
Minimum Solder Mask Sliver Constraint: (0.147mm < 0.254mm) Between Pad R3-1(6.3mm,4.25mm) on Top Layer And Pad
Minimum Solder Mask Sliver Constraint: (0.247mm < 0.254mm) Between Pad R3-1(6.3mm,4.25mm) on Top Layer And Pad
Minimum Solder Mask Sliver Constraint: (0.247mm < 0.254mm) Between Pad R3-2(7.2mm,4.25mm) on Top Layer And Pad
Minimum Solder Mask Sliver Constraint: (0.147mm < 0.254mm) Between Pad R4-1(6.3mm,5.25mm) on Top Layer And Pad
Minimum Solder Mask Sliver Constraint: (0.147mm < 0.254mm) Between Pad R5-1(7.2mm,7.25mm) on Top Layer And Pad
Minimum Solder Mask Sliver Constraint: (0.147mm < 0.254mm) Between Pad R6-1(3.95mm,10.75mm) on Top Layer And Pad
Minimum Solder Mask Sliver Constraint: (0.147mm < 0.254mm) Between Pad R7-1(2.65mm,2.3mm) on Top Layer And Pad
Minimum Solder Mask Sliver Constraint: (0.147mm < 0.254mm) Between Pad R8-1(13.925mm,22.525mm) on Top Layer And
Minimum Solder Mask Sliver Constraint: (0.234mm < 0.254mm) Between Pad R8-1(13.925mm,22.525mm) on Top Layer And
Minimum Solder Mask Sliver Constraint: (0.197mm < 0.254mm) Between Pad R8-2(14.825mm,22.525mm) on Top Layer And
Minimum Solder Mask Sliver Constraint: (0.147mm < 0.254mm) Between Pad R9-1(13.8mm,14mm) on Top Layer And Pad
Minimum Solder Mask Sliver Constraint: (0.197mm < 0.254mm) Between Pad TP10-1(16.25mm,4.4mm) on Top Layer And
Minimum Solder Mask Sliver Constraint: (0.197mm < 0.254mm) Between Pad TP10-1(16.25mm,4.4mm) on Top Layer And
Minimum Solder Mask Sliver Constraint: (0.197mm < 0.254mm) Between Pad TP1-1(16.25mm,18.4mm) on Top Layer And
Minimum Solder Mask Sliver Constraint: (0.197mm < 0.254mm) Between Pad TP1-1(16.25mm,18.4mm) on Top Layer And
Minimum Solder Mask Sliver Constraint: (0.197mm < 0.254mm) Between Pad TP13-1(16.25mm,10mm) on Top Layer And
Minimum Solder Mask Sliver Constraint: (0.122mm < 0.254mm) Between Pad TP3-1(5mm,2.25mm) on Top Layer And Pad
Minimum Solder Mask Sliver Constraint: (0.222mm < 0.254mm) Between Pad TP5-1(4.65mm,7.5mm) on Top Layer And Pad
Minimum Solder Mask Sliver Constraint: (0.147mm < 0.254mm) Between Pad U1-1(6.55mm,20.175mm) on Top Layer And
Minimum Solder Mask Sliver Constraint: (0.147mm < 0.254mm) Between Pad U1-2(7.5mm,20.175mm) on Top Layer And Pad
Minimum Solder Mask Sliver Constraint: (0.147mm < 0.254mm) Between Pad U2-1(2.8mm,3.625mm) on Top Layer And Pad
Minimum Solder Mask Sliver Constraint: (0.147mm < 0.254mm) Between Pad U2-2(3.75mm,3.625mm) on Top Layer And Pad
Minimum Solder Mask Sliver Constraint: (0.097mm < 0.254mm) Between Pad U3-1(14.925mm,11.55mm) on Top Layer And
Minimum Solder Mask Sliver Constraint: (0.097mm < 0.254mm) Between Pad U3-10(9.075mm,11.55mm) on Top Layer And
Minimum Solder Mask Sliver Constraint: (0.097mm < 0.254mm) Between Pad U3-11(9.075mm,5.95mm) on Top Layer And
Minimum Solder Mask Sliver Constraint: (0.097mm < 0.254mm) Between Pad U3-12(9.725mm,5.95mm) on Top Layer And
Minimum Solder Mask Sliver Constraint: (0.097mm < 0.254mm) Between Pad U3-13(10.375mm,5.95mm) on Top Layer And
Minimum Solder Mask Sliver Constraint: (0.097mm < 0.254mm) Between Pad U3-14(11.025mm,5.95mm) on Top Layer And
Minimum Solder Mask Sliver Constraint: (0.097mm < 0.254mm) Between Pad U3-15(11.675mm,5.95mm) on Top Layer And
Minimum Solder Mask Sliver Constraint: (0.097mm < 0.254mm) Between Pad U3-16(12.325mm,5.95mm) on Top Layer And
Minimum Solder Mask Sliver Constraint: (0.097mm < 0.254mm) Between Pad U3-17(12.975mm,5.95mm) on Top Layer And
Minimum Solder Mask Sliver Constraint: (0.097mm < 0.254mm) Between Pad U3-18(13.625mm,5.95mm) on Top Layer And
Minimum Solder Mask Sliver Constraint: (0.097mm < 0.254mm) Between Pad U3-19(14.275mm,5.95mm) on Top Layer And
Minimum Solder Mask Sliver Constraint: (0.097mm < 0.254mm) Between Pad U3-2(14.275mm,11.55mm) on Top Layer And
Minimum Solder Mask Sliver Constraint: (0.097mm < 0.254mm) Between Pad U3-3(13.625mm,11.55mm) on Top Layer And
Minimum Solder Mask Sliver Constraint: (0.097mm < 0.254mm) Between Pad U3-4(12.975mm,11.55mm) on Top Layer And
Minimum Solder Mask Sliver Constraint: (0.097mm < 0.254mm) Between Pad U3-5(12.325mm,11.55mm) on Top Layer And
Minimum Solder Mask Sliver Constraint: (0.097mm < 0.254mm) Between Pad U3-6(11.675mm,11.55mm) on Top Layer And
Minimum Solder Mask Sliver Constraint: (0.097mm < 0.254mm) Between Pad U3-7(11.025mm,11.55mm) on Top Layer And

Minimum Solder Mask Sliver (Gap=0.254mm) (All),(All)
Minimum Solder Mask Sliver Constraint: (0.097mm < 0.254mm) Between Pad U3-8(10.375mm,11.55mm) on Top Layer And
Minimum Solder Mask Sliver Constraint: (0.147mm < 0.254mm) Between Pad U5-1(2.55mm,20.175mm) on Top Layer And
Minimum Solder Mask Sliver Constraint: (0.147mm < 0.254mm) Between Pad U5-2(3.5mm,20.175mm) on Top Layer And Pad
Minimum Solder Mask Sliver Constraint: (0.197mm < 0.254mm) Between Pad U7-1(9.17mm,-2.4mm) on Top Layer And Pad
Minimum Solder Mask Sliver Constraint: (0.197mm < 0.254mm) Between Pad U7-2(9.17mm,-3.3mm) on Top Layer And Pad
Minimum Solder Mask Sliver Constraint: (0.197mm < 0.254mm) Between Pad U7-3(9.17mm,-4.2mm) on Top Layer And Pad
Minimum Solder Mask Sliver Constraint: (0.197mm < 0.254mm) Between Pad U7-5(11.33mm,-5.1mm) on Top Layer And Pad
Minimum Solder Mask Sliver Constraint: (0.197mm < 0.254mm) Between Pad U7-6(11.33mm,-4.2mm) on Top Layer And Pad
Minimum Solder Mask Sliver Constraint: (0.197mm < 0.254mm) Between Pad U7-7(11.33mm,-3.3mm) on Top Layer And Pad

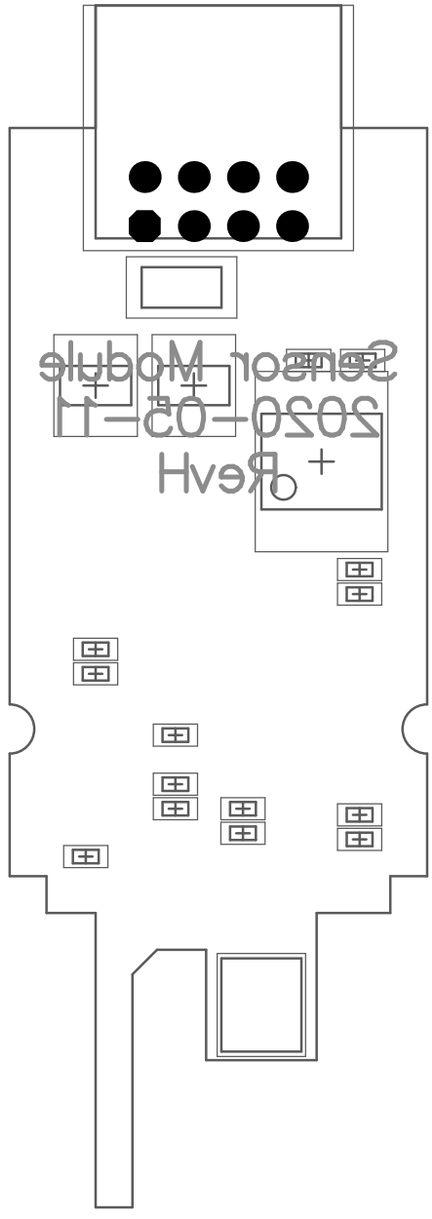
Silk To Solder Mask (Clearance=0.254mm) (IsPad),(All)
Silk To Solder Mask Clearance Constraint: (0.153mm < 0.254mm) Between Arc (13.25mm,23mm) on Top Overlay And Pad
Silk To Solder Mask Clearance Constraint: (0.197mm < 0.254mm) Between Arc (13.25mm,23mm) on Top Overlay And Pad
Silk To Solder Mask Clearance Constraint: (0.025mm < 0.254mm) Between Arc (15.65mm,11.55mm) on Top Overlay And Pa
Silk To Solder Mask Clearance Constraint: (0.162mm < 0.254mm) Between Arc (4.625mm,10.375mm) on Top Overlay And
Silk To Solder Mask Clearance Constraint: (0.155mm < 0.254mm) Between Pad F1-1(8.5mm,25.5mm) on Top Layer And
Silk To Solder Mask Clearance Constraint: (0.155mm < 0.254mm) Between Pad F1-1(8.5mm,25.5mm) on Top Layer And
Silk To Solder Mask Clearance Constraint: (0.155mm < 0.254mm) Between Pad F1-2(5.5mm,25.5mm) on Top Layer And
Silk To Solder Mask Clearance Constraint: (0.155mm < 0.254mm) Between Pad F1-2(5.5mm,25.5mm) on Top Layer And
Silk To Solder Mask Clearance Constraint: (0.25mm < 0.254mm) Between Pad U7-1(9.17mm,-2.4mm) on Top Layer And
Silk To Solder Mask Clearance Constraint: (0.1mm < 0.254mm) Between Pad U7-1(9.17mm,-2.4mm) on Top Layer And Trac
Silk To Solder Mask Clearance Constraint: (0.1mm < 0.254mm) Between Pad U7-2(9.17mm,-3.3mm) on Top Layer And Trac
Silk To Solder Mask Clearance Constraint: (0.1mm < 0.254mm) Between Pad U7-3(9.17mm,-4.2mm) on Top Layer And Trac
Silk To Solder Mask Clearance Constraint: (0.25mm < 0.254mm) Between Pad U7-4(9.17mm,-5.1mm) on Top Layer And
Silk To Solder Mask Clearance Constraint: (0.1mm < 0.254mm) Between Pad U7-4(9.17mm,-5.1mm) on Top Layer And Trac
Silk To Solder Mask Clearance Constraint: (0.1mm < 0.254mm) Between Pad U7-5(11.33mm,-5.1mm) on Top Layer And
Silk To Solder Mask Clearance Constraint: (0.25mm < 0.254mm) Between Pad U7-5(11.33mm,-5.1mm) on Top Layer And
Silk To Solder Mask Clearance Constraint: (0.1mm < 0.254mm) Between Pad U7-6(11.33mm,-4.2mm) on Top Layer And
Silk To Solder Mask Clearance Constraint: (0.1mm < 0.254mm) Between Pad U7-7(11.33mm,-3.3mm) on Top Layer And
Silk To Solder Mask Clearance Constraint: (0.1mm < 0.254mm) Between Pad U7-8(11.33mm,-2.4mm) on Top Layer And
Silk To Solder Mask Clearance Constraint: (0.25mm < 0.254mm) Between Pad U7-8(11.33mm,-2.4mm) on Top Layer And

Electrical Rules Check Report

Class	Document	Message
Warning	sensor_module.SchDoc	Net BOOT0 has no driving source (Pin R10-1, Pin U3-1)
Warning	sensor_module.SchDoc	Net SENSE+ has no driving source (Pin R1-2, Pin R3-1, Pin R7-2, Pin TP3-1, Pin U2-3)
Warning	sensor_module.SchDoc	Net SENSE- has no driving source (Pin C2-2, Pin C3-2, Pin R2-2, Pin R4-1, Pin R5-2, Pin TP4-1, Pin U2-4)
Warning	sensor_module.SchDoc	Net SENSOR_RX+ has no driving source (Pin D2-6, Pin J1-5, Pin U4-8)
Warning	sensor_module.SchDoc	Net SENSOR_RX- has no driving source (Pin D2-4, Pin J1-6, Pin U4-7)



Layer	Name	Material	Thickness	Constant	Gerber
	Top Overlay				GTO
	Top Solder	Solder Resist	0.013mm	3.8	GTS
1	Top Layer	Copper	0.036mm		GTL
	Dielectric 1	FR-4	0.502mm	4.8	
2	Bottom Layer	Copper	0.036mm		GBL
	Bottom Solder	Solder Resist	0.013mm	3.8	GBS
	Bottom Overlay				GBO
Total board thickness:			0.599mm		


Sensor Module
2020-03-11
RevH